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SX9300

Ultra Low Power, Dual Channel
Smart Proximity SAR Compliant Solution

WIRELESS & SENSING

GENERAL DESCRIPTION

The SX9300 is the world's first dual channel capacitive Specific Absorption Rate (SAR) controller that accurately discriminates between an inanimate object and human body proximity. The resulting detection is used in portable electronic devices to reduce and control radio-frequency (RF) emission power in the presence of a human body, enabling significant performance advantages for manufacturers of electronic devices with electro-magnetic radiation sources to meet stringent emission regulations' criteria and Specific Absorption Rate (SAR) standards. Operating directly from an input supply voltage of 2.7 to 5.5V, the SX9300 outputs its data via a 1.65 – 5.5V host compatible I2C serial bus.

The I2C serial communication bus port is compatible with 1.8V host control to report body detection/proximity and to facilitate parameter settings adjustment. Upon proximity detection, the NIRQ output asserts, enabling the user to either determine the relative proximity distance, or simply obtain an indication of detection.

The SX9300 includes an on-chip auto-calibration controller that regularly performs sensitivity adjustments to maintain peak performance over a wide variation of temperature, humidity and noise environments, providing simplified product development and enhanced performance. A dedicated transmit enable (TXEN) pin is available to synchronize proximity measurements to RF transmission, enabling very low supply current and high noise immunity by only measuring proximity when requested.

KEY PRODUCT FEATURES

- **2.7 – 5.5V Input Supply Voltage**
- **Dual SAR Capacitive Sensor Inputs**
  - On-Chip SAR Engine For Body versus Inanimate Object Detection
  - Down to 0.08 fF Capacitance Resolution
  - Stable Proximity Sensing With Temperature
  - 20mm detection distance
  - Capacitance Offset Compensation up to 30pF
- **Active Sensor Guarding**
- **Automatic Calibration**
- **Ultra Low Power Consumption:**
  - Active Mode: 170 uA
  - Doze Mode: 18 uA
  - Sleep Mode: 2.5 uA
- **400kHz I2C Serial Interface**
  - Four programmable I2C Sub-Addresses
  - Input Levels Compatible with 1.8V Host Processors
- **Open Drain NIRQ Interrupt pin**
- **Three (3) Reset Sources: POR, NRST pin, Soft Reset**
- **-40°C to +85°C Operation**
- **Compact Size: 3 x 3mm Thin QFN package**
- **Pb & Halogen Free, RoHS/WEEE compliant**

APPLICATIONS

- SAR Compliant Systems
- Notebooks
- Tablets
- Mobile Phones
- Mobile Hot Spots

ORDERING INFORMATION

Part Number	Package	Marking
SX9300IULTRT [1]	QFN-20	ZM5C
SX9300EVKA	Eval. Kit	-

[1] 3000 Units/reel

TYPICAL APPLICATION CIRCUIT

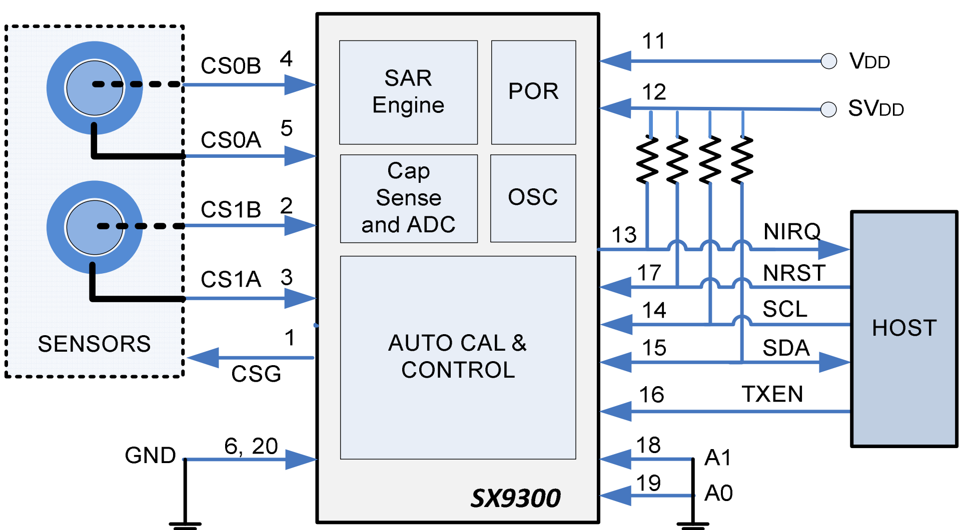

Table of Contents

1 General Description

1.1 Pin Diagram

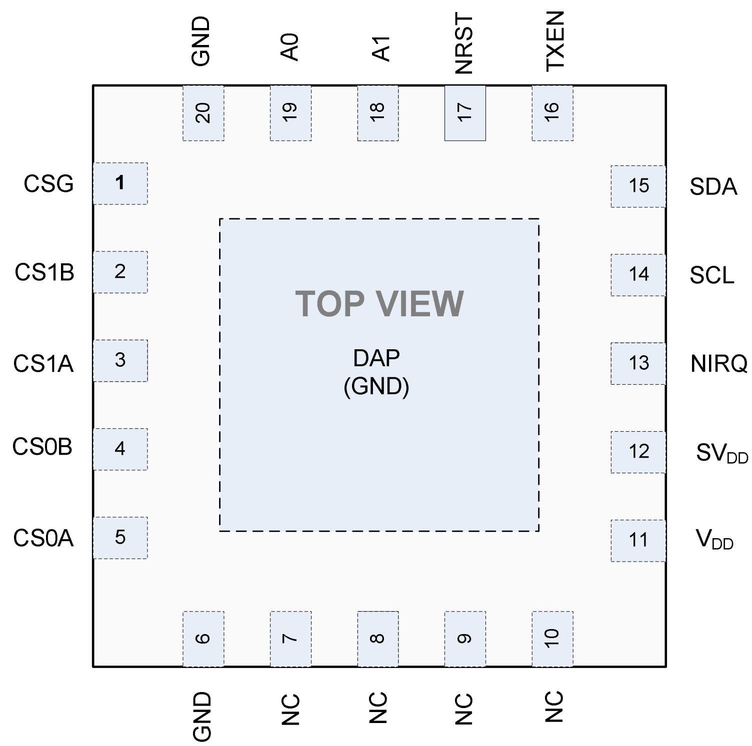

Figure 1: Pin Diagram

1.2 Marking Information

Figure 2: Marking Information

1.3 Pin Description

Number	Name	Type	Description
1	CSG	Analog	Capacitive Sensor Guard/Shield
2	CS1B	Analog	Capacitive Sensor B (inner) of pair 1
3	CS1A	Analog	Capacitive Sensor A (outer) of pair 1
4	CS0B	Analog	Capacitive Sensor B (inner) of pair 0
5	CS0A	Analog	Capacitive Sensor A (outer) of pair 0
6	GND	Ground	Ground
7	NC	Not Used	Do Not Connect
8	NC	Not Used	Do Not Connect
9	NC	Not Used	Do Not Connect
10	NC	Not Used	Do Not Connect
11	V_{DD}	Power	Core power supply
12	SV_{DD}	Power	Host interface power supply. Must be ≤V_{DD} at all times (including during power-up and power-down)
13	NIRQ	Digital Output	Interrupt request, active LOW, requires pull-up resistor to SV_{DD}
14	SCL	Digital Input	I2C Clock, requires pull-up resistor to SV_{DD}
15	SDA	Digital I/O	I2C Data, requires pull-up resistor to SV_{DD}
16	TXEN	Digital Input	Transmit Enable, active HIGH (Tie to SV_{DD} if not used).
17	NRST	Digital Input	External reset, active LOW (Tie to SV_{DD} if not used).
18	A1	Digital Input	I2C Sub-Address, connect to GND or V_{DD}
19	A0	Digital Input	I2C Sub-Address, connect to GND or V_{DD}
20	GND	Ground	Ground
DAP	GND	Ground	Exposed Pad. Connect to Ground

Table 1: Pin Description

1.4 Acronyms

DAP	Die Attach Paddle
SAR	Specific Absorption Rate
RF	Radio Frequency

2 ELECTRICAL CHARACTERISTICS

2.1 Absolute Maximum Ratings

Stresses above the values listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these, or any other conditions beyond the "Operating Conditions", is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability and proper functionality.

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V_{DD}	-0.5	6.0	V
	SV_{DD}	-0.5	6.0	
Input Voltage (non-supply pins)	V_{IN}	-0.5	V_{DD}+0.3	
Input Current (non-supply pins)	I_{IN}	-10	10	mA
Operating Junction Temperature	T_{JCT}	-40	125	°C
Reflow Temperature	T_{RE}	-	260	
Storage Temperature	T_{STOR}	-50	150	
ESD HBM (Human Body model, to JESD22-A114)	ESD_{HBM}	8	-	kV

Table 2: Absolute Maximum Ratings

2.2 Operating Conditions

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V_{DD}	2.7	5.5	V
	SV_{DD}	1.65	V_{DD}	
Ambient Temperature	T_A	-40	85	°C

Table 3: Operating Conditions

Note: During power-up or power-down, SVDD must be less than or equal to VDD

2.3 Thermal Characteristics

Parameter	Symbol	Typical	Unit
Thermal Resistance – Junction to Air (Static Airflow)	θ_{JA}	34	°C/W

Table 4: Thermal Characteristics

Note: θ_{JA} is calculated from a package in still air, mounted to 3" x 4.5", 4-layer FR4 PCB with thermal vias under exposed pad per JESD51 standards.

2.4 Electrical Specifications

All values are valid within the operating conditions unless otherwise specified.
Typical values are given for T_A= +25°C, VDD=SVDD=3.3V unless otherwise specified.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Current Consumption						
Sleep (no sensor enabled)	I_{SLEEP}	Power down, all analog circuits shut down. (I2C listening)	-	2.5	-	uA
Doze (all sensors enabled)	I_{DOZE}	SCANPERIOD = 200ms DOZEPERIOD = 2xSCANPERIOD FREQ = 167kHz RESOLUTION = Medium VDD = 5V	-	18	-	uA
Active (all sensors enabled)	I_{ACTIVE}	SCANPERIOD = 30ms FREQ = 167kHz RESOLUTION = Medium VDD = 5V	-	170	-	uA
Outputs: SDA, NIRQ						
Output Current at Output Low Voltage	I_{OL}	VOL = 0.4V	6	-	-	mA
Maximum Output LOW Voltage	V_{OL}(Max)	SV_{DD} > 2V	-	-	0.4	V
		SV_{DD} ≤ 2V	-	-	0.2 x SV_{DD}	V
Inputs: SCL, SDA, TXEN						
Input logic high	V_{IH}		0.8 x SVDD	-	SVDD + 0.3	V
Input logic low	V_{IL}		-0.3	-	0.25 x SVDD	V
Input leakage current	I_L	CMOS input	-1	-	1	uA
Hysteresis	V_{HYS}	SV_{DD} > 2V	-	0.05x SV_{DD}	-	V
		SV_{DD}≤ 2V	-	0.1x SV_{DD}	-	V
TXEN Delay	$TXEN_{ACTDLY}$	Delay between TXEN rising edge and SX9300 starting measurements	-	100	-	µs
Inputs: A0, A1						
Input logic high	V_{IH}		0.7 x VDD	-	VDD + 0.3	V
Input logic low	V_{IL}		-0.3	-	0.3 x VDD	V

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Input: NRST						
Input logic high	V_{IH}	SV_{DD}> 2V	0.7 x SV_{DD}	-	SV_{DD} + 0.3	V
		SV_{DD} ≤ 2V	0.75 x SV_{DD}	-		V
Input logic low	V_{IL}	SV_{DD}> 2V	-	-	0.6	V
		SV_{DD} ≤ 2V	-	-	0.3 x SV_{DD}	V
NRST minimum pulse width	$T_{RESETPW}$		2	-	-	µs
Start-up						
Power-up time	T_{POR}		-	1	-	ms

Table 5: Electrical Specifications

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
I2C Timing Specifications (Cf. Figure 3 and Figure 4 below)						
SCL clock frequency	f_{SCL}		-	-	400	kHz
SCL low period	t_{LOW}		1.3	-	-	us
SCL high period	t_{HIGH}		0.6	-	-	
Data setup time	$t_{SU;DAT}$		0.1	-	-	
Data hold time	$t_{HD;DAT}$		0	-	-	
Repeated start setup time	$t_{SU;STA}$		0.6	-	-	
Start condition hold time	$t_{HD;STA}$		0.6	-	-	
Stop condition setup time	$t_{SU;STO}$		0.6	-	-	
Bus free time between stop and start	t_{BUF}		1.3	-	-	
Input glitch suppression	t_{SP}	Note 1	-	-	50	ns

Note 1: Minimum glitch amplitude is $0.7V_{DD}$ at High level and Maximum $0.3V_{DD}$ at Low level.

Table 6: I2C Timing Specifications

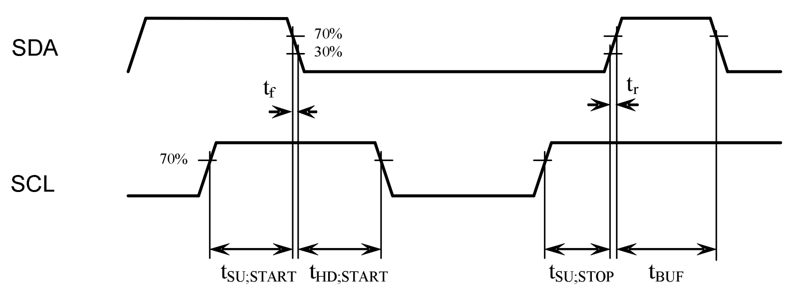

Figure 3: I2C Start and Stop Timing

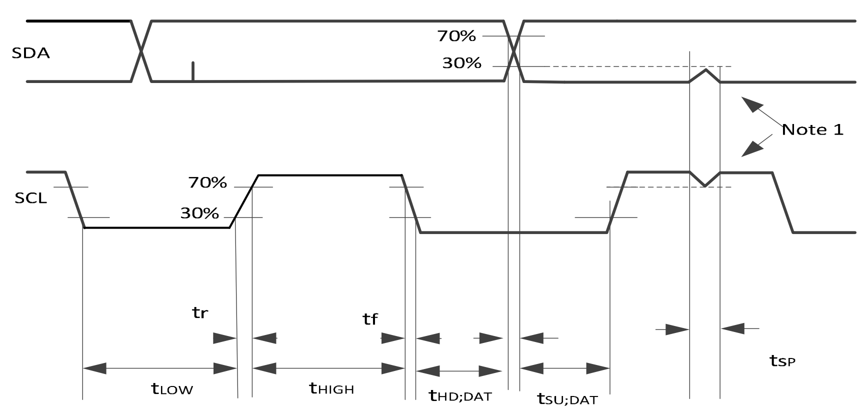

Figure 4: I2C Data Timing

3 PROXIMITY SENSING INTERFACE

3.1 Introduction

The purpose of the proximity sensing interface is to detect when a conductive object (usually a body part i.e. finger, palm, face, etc) is in the proximity of the system. Note that proximity sensing can be done thru the air or thru a solid (typically plastic) overlay (also called “touch” sensing).

The chip’s proximity sensing interface is based on capacitive sensing technology. An overview is given in figure below.

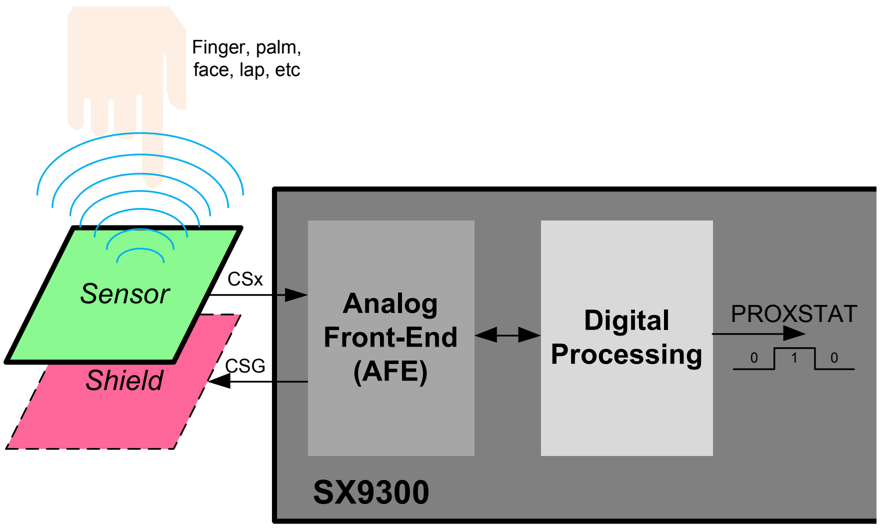

Figure 5: Proximity Sensing Interface Overview

- The sensor can be a simple copper area on a PCB or FPC for example. Its capacitance (to ground) will vary when a conductive object is moving in its proximity.
- The optional shield can be also be a simple copper area on a PCB or FPC below/under/around the sensor. It is used to protect the sensor against potential surrounding noise sources and improve its global performance. It also brings directivity to the sensing, for example sensing objects approaching from top only.
- The analog front-end (AFE) performs the raw sensor’s capacitance measurement and converts it into a digital value. It also controls the shield. See §3.3 for more details.
- The digital processing block computes the raw capacitance measurement from the AFE and extracts a binary information PROXSTAT corresponding to the proximity status, i.e. object is “Far” or “Close”. It also triggers AFE operations (compensation, etc). See §3.4 for more details.

3.2 Scan Period

To save power and since the proximity event is slow by nature, the chip will be waken-up regularly at every programmed scan period (SCANPERIOD) to first sense sequentially each of the enabled CSx pins and then process new proximity samples/info. The chip will be in idle mode most of the time. This is illustrated in figure below

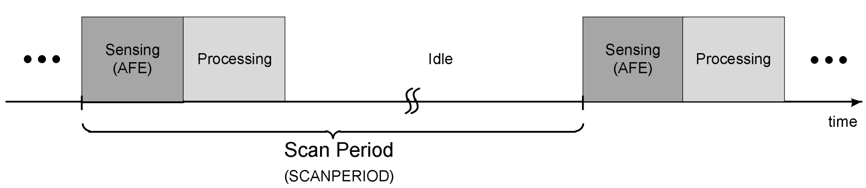

Figure 6: Proximity Sensing Sequencing

The sensing and processing phase's durations vary with the number of sensors enabled, the sampling frequency, and the resolution programmed. During the Idle phase, the SX9300's analog circuits are turned off. Upon expiry of the idle timer, a new scan period cycle begins.

The scan period determines the minimum reaction time (actual/final reaction time also depends on debounce and filtering settings) and can be programmed from 30ms to 400ms.

3.3 Analog Front-End (AFE)

3.3.1 Capacitive Sensing Basics

Capacitive sensing is the art of measuring a small variation of capacitance in a noisy environment. As mentioned above, the chip's proximity sensing interface is based on capacitive sensing technology. In order to illustrate some of the user choices and compromises required when using this technology it is useful to understand its basic principles.

To illustrate the principle of capacitive sensing we will use the simplest implementation where the sensor is a copper plate on a PCB.

The figure below shows a cross-section and top view of a typical capacitive sensing implementation. The sensor connected to the chip is a simple copper area on top layer of the PCB. It is usually surrounded (shielded) by ground for noise immunity (shield function) but also indirectly couples via the grounds areas of the rest of the system (PCB ground traces/planes, housing, etc). For obvious reasons (design, isolation, robustness …) the sensor is stacked behind an overlay which is usually integrated in the housing of the complete system.

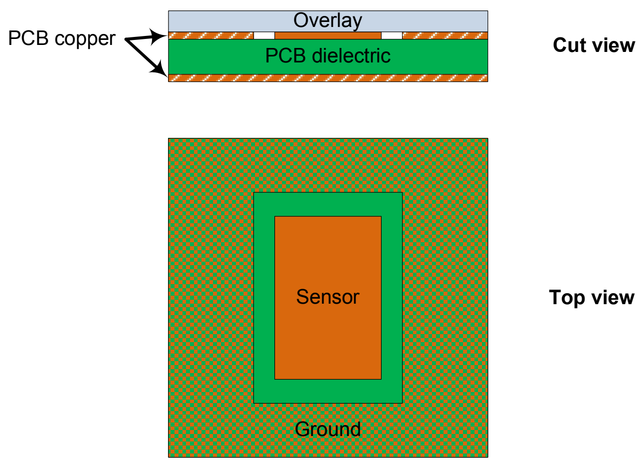

Figure 7: Typical Capacitive Sensing Implementation

When the conductive object to be detected (finger/palm/face, etc) is not present, the sensor only sees an inherent capacitance value C_{Env} created by its electrical field's interaction with the environment, in particular with ground areas.

When the conductive object (finger/palm/face, etc) approaches, the electrical field around the sensor will be modified and the total capacitance seen by the sensor increased by the user capacitance C_{User}. This phenomenon is illustrated in the figure below.

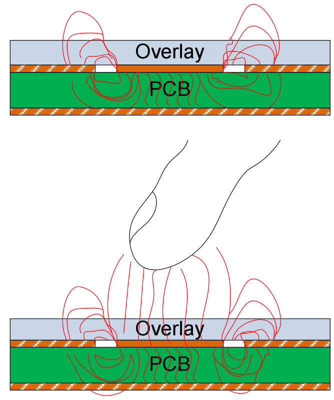

Figure 8: Proximity Effect on Electrical Field and Sensor Capacitance

The challenge of capacitive sensing is to detect this relatively small variation of C_{Sensor} (C_{User} usually contributes for a few percent only) and differentiate it from environmental noise (C_{Env} also slowly varies together with the environment characteristics like temperature, etc). For this purpose, the chip integrates an auto offset compensation mechanism which dynamically monitors and removes the C_{Env} component to extract and process C_{User} only. See §3.3.5 for more details.

In first order, C_{User} can be estimated by the formula below:

$$C_{User} = \frac{\varepsilon_0 \cdot \varepsilon_r \cdot A}{d}$$

A is the common area between the two electrodes hence the common area between the user's finger/palm/face and the sensor.

d is the distance between the two electrodes hence the proximity distance between the user and the system.

ε_0 is the free space permittivity and is equal to 8.85 10e-12 F/m (constant)

ε_r is the dielectric relative permittivity.

Typical permittivity of some common materials is given in the table below.

Material	**Typical** ε_r
Glass	8
FR4	5
Acrylic Glass	3
Wood	2
Air	**1**

Table 7: Typical Permittivity of Some Common Materials

From the discussions above we can conclude that the most robust and efficient design will be the one that minimizes C_{Env} value and variations while improving C_{User}.

3.3.2 AFE Block Diagram

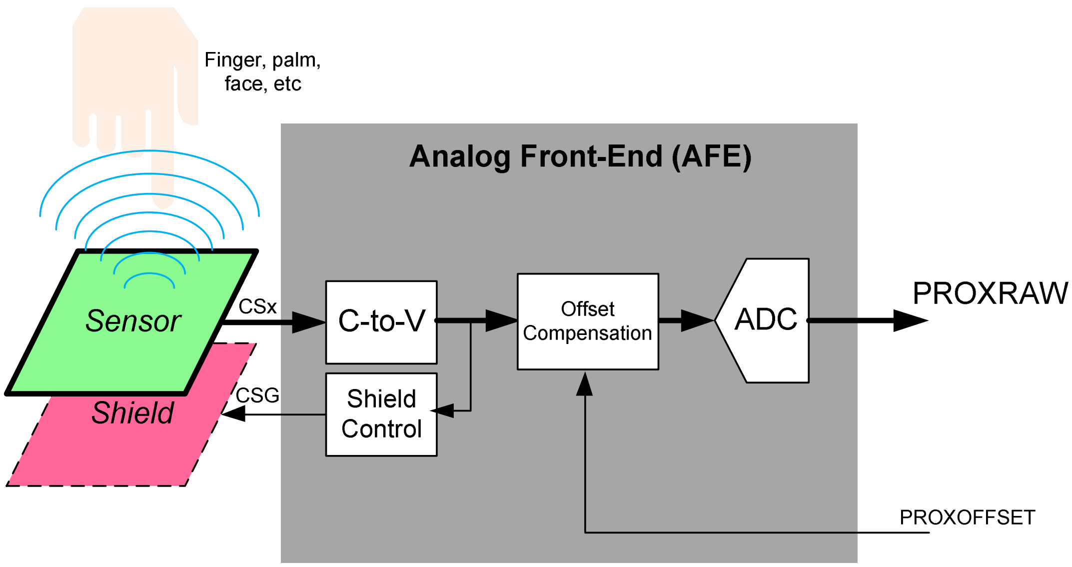

Figure 9: Analog Front-End Block Diagram

3.3.3 Capacitance-to-Voltage Conversion (C-to-V)

The sensitivity of the interface is defined by RANGE and GAIN parameters.

PROXFREQ defines the operating frequency of the interface and should be set as high as possible for power consumption reasons.

3.3.4 Shield Control

SHIELDEN allows enabling or disabling the shield function.

3.3.5 Offset Compensation

Offset compensation consists in performing a one-time measurement of C_{Env} and subtracting it to the total capacitance C_{Sensor} in order to feed the ADC with the closest contribution of C_{User} only.

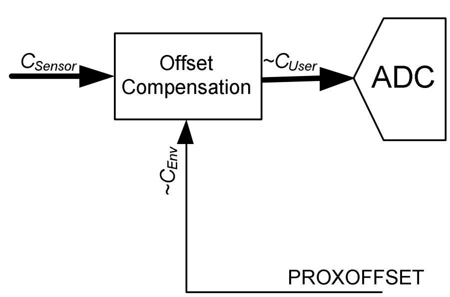

Figure 10: Offset Compensation Block Diagram

The ADC input C_{User} is the total capacitance C_{Sensor} to which C_{Env} is subtracted.

There are five possible compensation sources which are illustrated in the figure below. When set to 1 by any of these sources, COMPSTAT will only be reset once the compensation is completed.

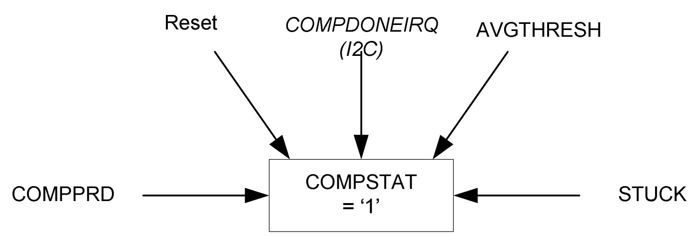

Figure 11: Compensation Request Sources

- Reset: a compensation for all sensors is automatically requested when a reset is performed (power-up, NRST pin, RegReset)
- COMPDONEIRQ (I2C): a compensation for all sensors can be manually requested anytime by the host through I2C interface by writing a 1 into COMPDONEIRQ.
- AVGTHRESH: a compensation for all sensors or only the affected one (depending on COMPMETHOD) can be automatically requested if it is detected that C_{Env} has drifted beyond a predefined range programmed by the host.
- COMPPRD: a compensation can be automatically requested at a predefined rate programmed by the host.
- STUCK: a compensation can be automatically requested if it is detected that the proximity "Close" state lasts longer than a predefined duration programmed by the host.

Please note that the compensation request flag can be set anytime but the compensation itself is always done at the beginning of a scan period to keep all parameters coherent.
Also, when compensation occurs, all PROXSTAT flags turn OFF (ie no proximity detected) independently from the user's potential actual presence.

3.3.6 Analog-to-Digital Conversion (ADC)

An ADC is used to convert the analog capacitance information into a digital word PROXRAW.

3.4 Digital Processing

3.4.1 Overview

The main purpose of the digital processing block is to convert the raw capacitance information coming from the AFE (PROXRAW) into a robust and reliable digital flag (PROXSTAT) indicating if something is close to the proximity sensor.

The offset compensation performed in the AFE is a one-time measurement. However, the environment capacitance C_{Env} may vary with time (temperature, nearby objects, etc). Hence, in order to get the best estimation of C_{User} (PROXDIFF) it is needed to dynamically track and subtract C_{Env} variations. This is performed by filtering PROXUSEFUL to extract its slow variations (PROXAVG).

PROXDIFF is then compared to user programmable threshold (PROXTHRESH) to extract PROXSTAT flag.

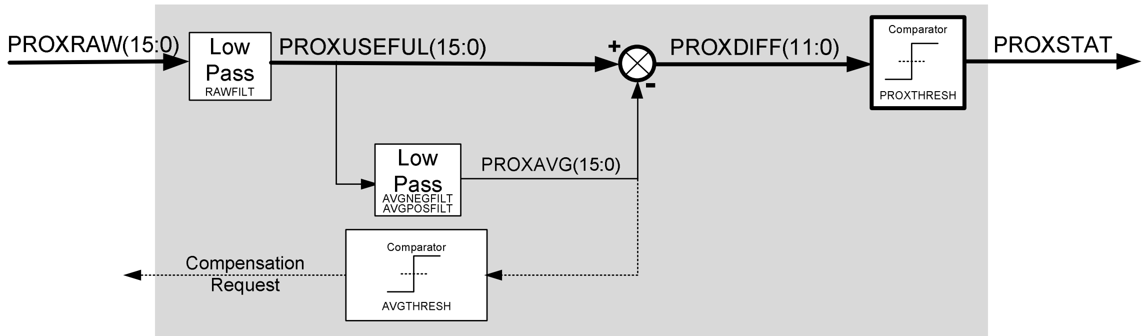

Figure 12: Digital Processing Block Diagram

Digital processing sequencing is illustrated in figure below. At every scan period wake-up, the block updates sequentially PROXRAW, PROXUSEFUL, PROXAVG, PROXDIFF and PROXSTAT before going back to Idle mode.

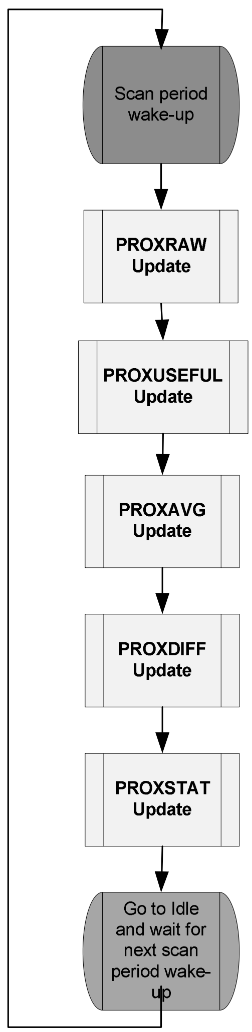

Figure 13: Digital Processing Sequencing

Digital processing block also updates COMPSTAT (set when compensation is currently pending execution or completion)

3.4.2 PROXRAW Update

PROXRAW update consists mainly in starting the AFE and waiting for the new PROXRAW values (one for each CSx/sensor pin) to be ready. If compensation was pending it is performed first.

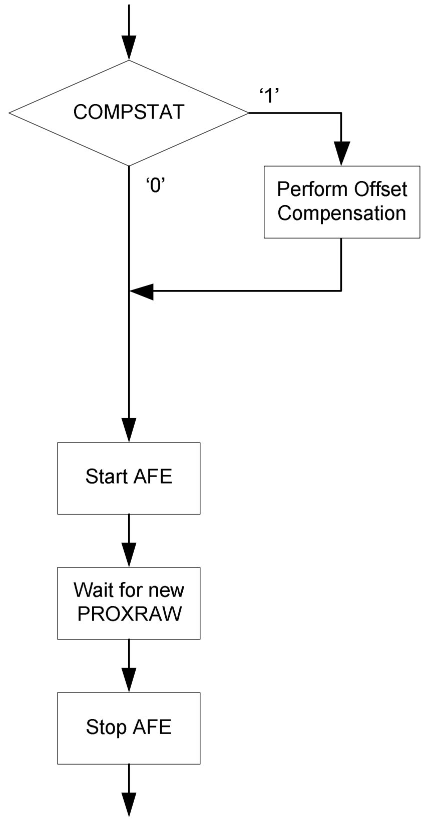

Figure 14: ProxRaw Update

Note that PROXRAW is not available in the "Sensor Data Readback" section of the registers. If needed it can be observed by setting RAWFILT=00 and reading PROXUSEFUL.

3.4.3 PROXUSEFUL Update

PROXUSEFUL update consists in filtering PROXRAW upfront to remove its potential high frequencies components(system noise, interferer, etc) and extract only user activity (few Hz max) and slow environment changes.

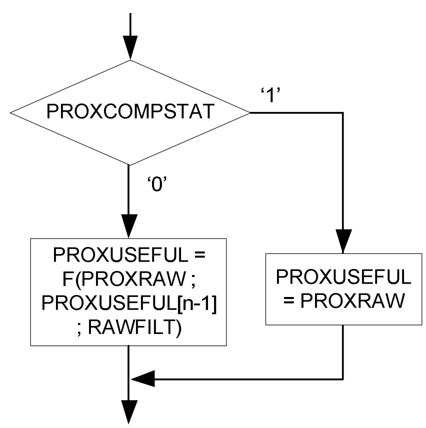

Figure 15: PROXUSEFUL Update

3.4.4 PROXAVG Update

PROXAVG update consists in averaging PROXUSEFUL to ignore its “fast” variations (i.e. user finger/palm/hand) and extract only the very slow variations of environment capacitance C_{Env}.

One can program a debounced threshold (AVGTHRESH/AVGDEB) to define a range within which PROXAVG can vary without triggering compensation (i.e. small acceptable environment drift).

Large positive values of PROXUSEFUL are considered as normal (user finger/hand/head) but large negative values are considered abnormal and should be compensated quickly. For this purpose, the averaging filter coefficient can be set independently for positive and negative variations via AVGPOSFILT and AVGNEGFILT. Typically we have AVGPOSFILT > AVGNEGFILT to filter out (abnormal) negative events faster.

To prevent PROXAVG to be “corrupted” by user activity (should only reflect environmental changes) it is frozen when proximity is detected.

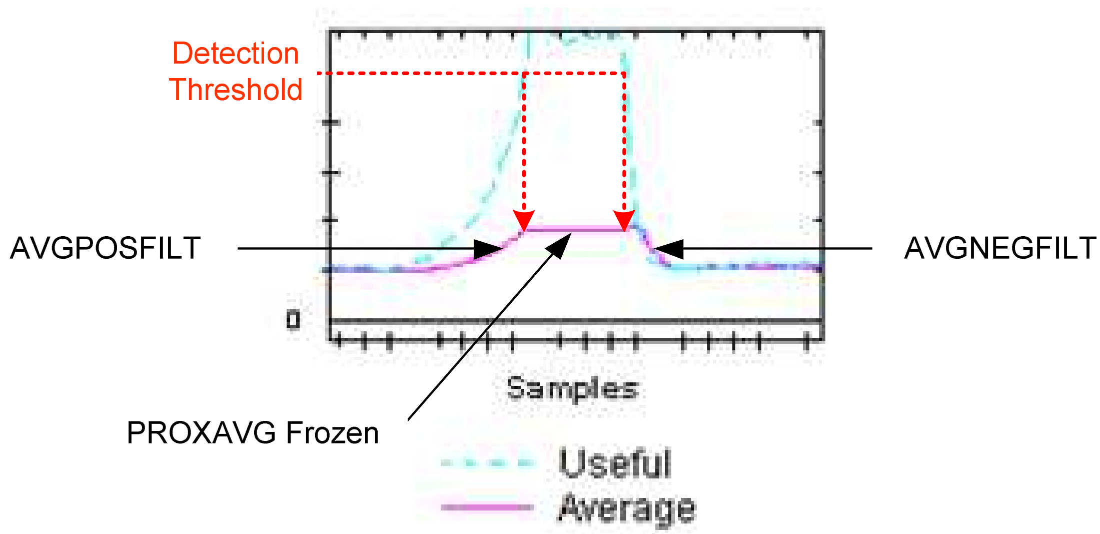

Figure 16: ProxAvg vs Proximity Event

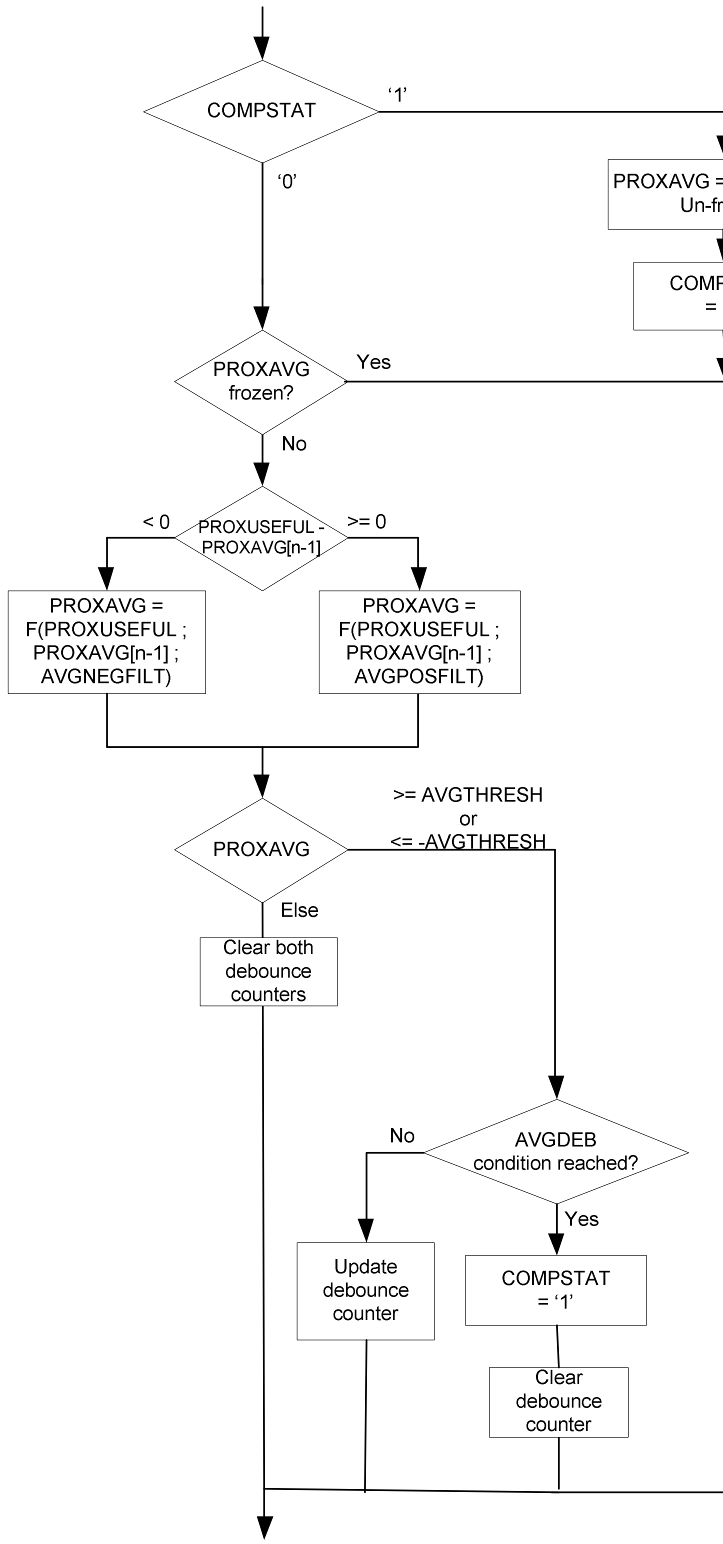

Figure 17: ProxAvg Update

3.4.5 PROXDIFF Update

PROXDIFF update consists in the complementary operation i.e. subtracting PROXAVG to PROXUSEFUL to ignore slow capacitances variations (C_{Env}) and extract only the user related variations i.e. C_{User}.

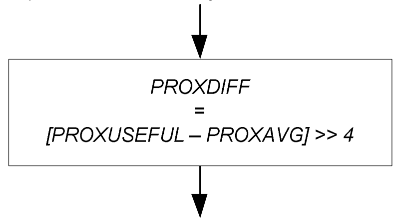

Figure 18: ProxDiff Update

Note that only the 12 upper bits of [PROXUSEFUL – PROXAVG] are kept for PROXDIFF.

3.4.6 PROXSTAT Update

PROXSTAT update consists in taking PROXDIFF information (C_{User}), comparing it with a user programmable threshold PROXTHRESH and finally updating PROXSTAT accordingly. When PROXSTAT=1, PROXAVG is frozen to prevent the user proximity signal averaging and hence absorbed into C_{Env}.

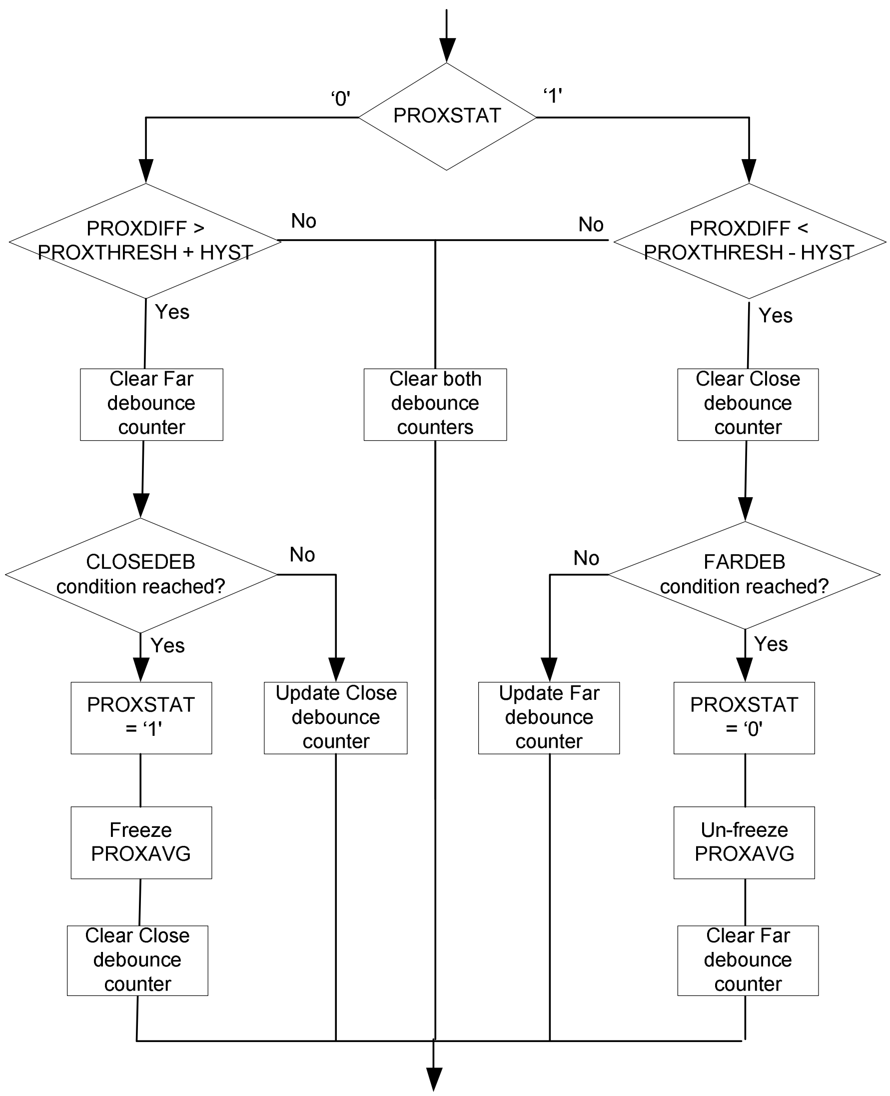

Figure 19: PROXSTAT Update

3.5 Host Operation

An interrupt can be triggered when the user is detected to be close (in range), detected to be far (out of range), or both (CLOSEIRQEN, FARIRQEN).

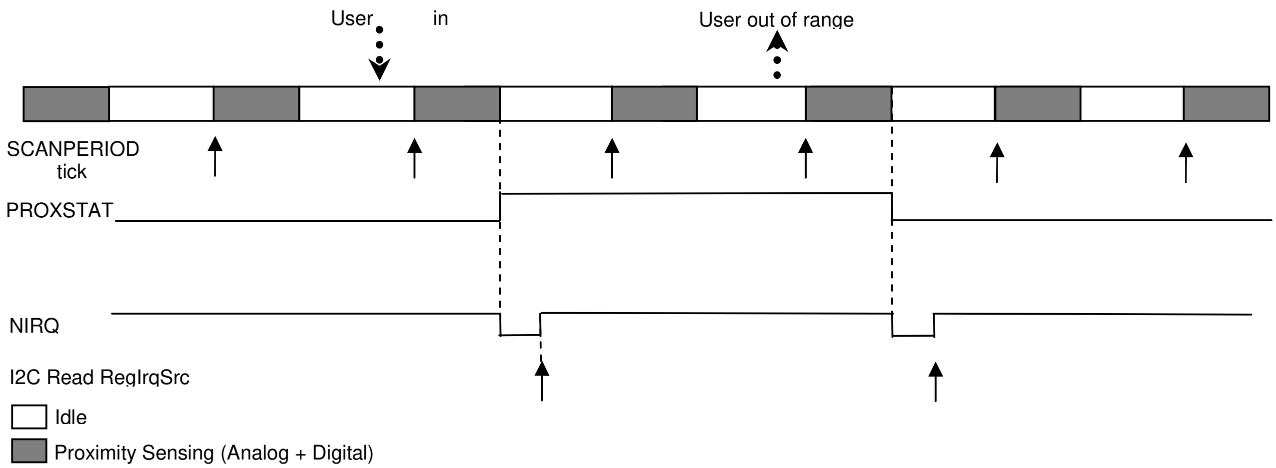

Figure 20: Proximity Sensing Host Operation (RegIrqMsk[6:3] = 1100)

An interrupt can also be triggered at the end of each proximity sensing operation, indicating to the host when the proximity sensing block is running (CONVDONEIRQEN). This may be used by the host to synchronize noisy system operations or to read sensor data (PROXUSEFUL, PROXAVG, PROXDIFF) synchronously for monitoring purposes.

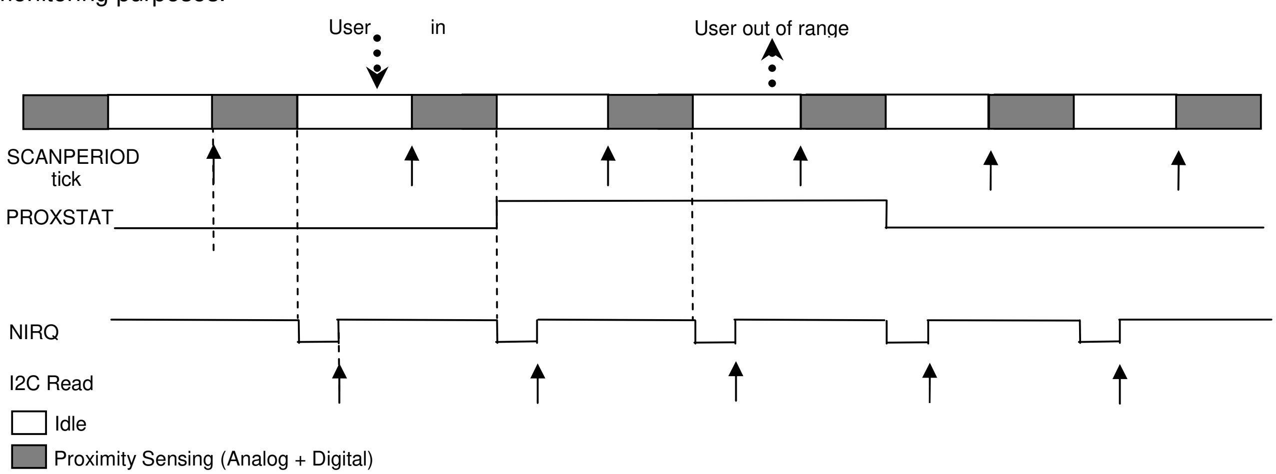

Figure 21: Proximity Sensing Host Operation (RegIrqMsk[6:3] = 0001)

In both cases above, an interrupt can also be triggered at the end of compensation (COMPDONEIRQEN).

3.6 Operational Modes

3.6.1 Active

Active mode has the shortest scan periods, typically 30ms. In this mode, all enabled sensors are scanned and information data is processed within this interval. The Active scan period is user configurable (SCANPERIOD) and can be extended up to 400ms.

3.6.2 Doze

In some applications, the reaction/sensing time needs to be fast when the user is present (proximity detected), but can be slow when not detection has been done for some time.

The Doze mode, when enabled (DOZEEN), allows the chip to automatically switch between a fast scan period (SCANPERIOD) during proximity detection and a slow scan period (DOZEPERIOD) when no proximity is being detected (up to 6.4s). This allows reaching low average power consumption values at the expense obviously of longer reaction times.

As soon as proximity is detected on any sensor, the chip will automatically switch to Active mode while when it has not detected an object for DOZEPERIOD, it will automatically switch to Doze mode.

3.6.3 Sleep

Sleep mode can be entered by disabling all sensors (SENSOREN=0000). It places the SX9300 in its lowest power mode, with sensor scanning completely disabled and idle period set to continuous. In this mode, only the I2C serial bus is active. Enabling any sensor will make the chip leave Sleep mode (for Doze if enabled, else Active mode)

3.6.4 TXEN Pin

The TXEN input enables proximity sensing when HIGH, likewise when the TXEN input is LOW, the SX9300 is in Sleep mode. Specifically, on the rising edge of TXEN the SX9300 will begin measuring the sensors normally at the programmed rate (SCANPERIOD, DOZEPERIOD) as long as TXEN remains HIGH. When TXEN goes LOW the current measurement sequence will complete and then measurement will cease until the next rising edge of TXEN.

This feature can be used to synchronize proximity sensing with noisy and/or RF activity for example.

4 SMART SAR ENGINE

4.1 Introduction

In addition to the proximity sensing interface, the SX9300 also embeds the world's first smart SAR engine which is able to discriminate between proximity generated by low permittivity (table) and high permittivity objects (body). This is typically useful for Specific Absorption Rate (SAR) applications in portable devices (tablets, cellphones, etc) where international regulations (FCC, ETSI, etc) impose to reduce RF power in the presence of human body for safety reasons.

Typical capacitive sensing solutions are not able to discriminate between proximity detection generated when a tablet for example is sitting on a table (no need to reduce RF power) vs when it is sitting the user's lap (need to reduce RF power) resulting in RF power and hence user's experience reduced significantly even when it is not needed.

The SX9300's unique smart SAR engine allows reducing RF power only in the presence of body (high permittivity material) and hence offering significantly better user experience while still conforming to safety regulations.

4.2 Sensor Design

In order to use SX9300's smart SAR engine, the sensors design must follow a few rules which are described in this section.

Each smart SAR sensor is physically made of two sensors (outer and inner) connected respectively to pins CSxA and CSxB. In the drawing below, the dark areas represent copper (conductor) and the light areas represents a non-conductor (spacing between the two copper areas).

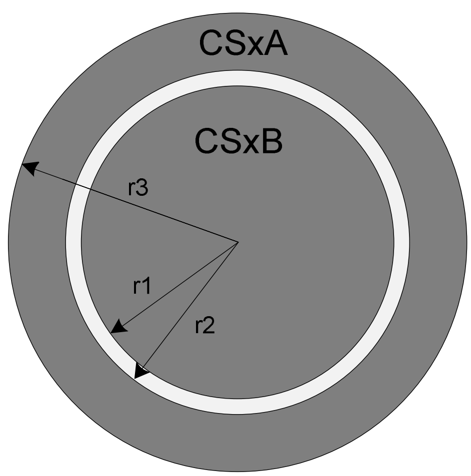

Figure 22: Typical Smart SAR Capacitive Sensor

IMPORTANT: The "A" and "B" sensors cannot be swapped. The outer copper area is always the "A" sensor, and the inner copper area is always the "B" sensor else the smart SAR engine will not operate properly.

For each pair, the copper areas of CSxB and CSxA pads must be designed to be equal (as equal as the FPC/PCB technology tolerance allows).

Figure above illustrates an example of circular shape but smart SAR sensors can of course be designed in a variety of shapes (square, rectangular) depending on the physical/mechanical constraints of the system.

One SX9300 can support up to two pairs of sensors i.e. two smart SAR sensors.

4.3 Processing

The smart SAR engine is active for a pair of sensors when its CSxPROXSTAT is set i.e. both CSxA and CSxB's internal PROXSTAT values are set (i.e. both sensors of a the same pair have detected proximity).

When active, the smart SAR engine computes two real time values called delta and ratio (SARDELTA, SARRATIO), compares them to their respective user-defined debounced thresholds (SARDELTATHRESH, SARRATIOTHRESH, SARDEB) and updates CSxBODYSTAT accordingly (set to 1 when both delta and ratio exceed their respective thresholds).

Note that an hysteresis derivated from HYST is automatically applied to delta and ratio thresholds as defined below:

HYST	Delta Threshold Hysteresis	Ratio Threshold Hysteresis
00	2	2
01	4	4
10	8	6
11	16	8

Table 8: Delta/Ratio Thresholds Hysteresis

5 I2C INTERFACE

5.1 Introduction

The I2C implemented on the SX9300 and used by the host to interact with it is compliant with:

- Standard (100kb/s) and fast mode (400kb/s)
- Slave mode
- 7-bit address (default is 0x28 assuming A1=A0=0)

The SX9300 has two I/O pins (A0 and A1) that provides four possible, user selectable I2C addresses:

A1	A0	Address
0	0	0x28
0	1	0x29
1	0	0x2A
1	1	0x2B

Table 9: I2C Sub-Address Selection

The host can use the I2C to read and write data at any time, and these changes are effective immediately. Therefore the user should ideally disable the sensor before changing settings, or discard the results while changing.

5.2 I2C Write

The format of the I2C write is given in Figure 12. After the start condition [S], the slave address (SA) is sent, followed by an eighth bit (‘0’) indicating a Write. The SX9300 then Acknowledges [A] that it is being addressed, and the Master sends an 8 bit Data Byte consisting of the SX9300 Register Address (RA). The Slave Acknowledges [A] and the master sends the appropriate 8 bit Data Byte (WD0). Again the Slave Acknowledges [A]. In case the master needs to write more data, a succeeding 8 bit Data Byte will follow (WD1), acknowledged by the slave [A]. This sequence will be repeated until the master terminates the transfer with the Stop condition [P].

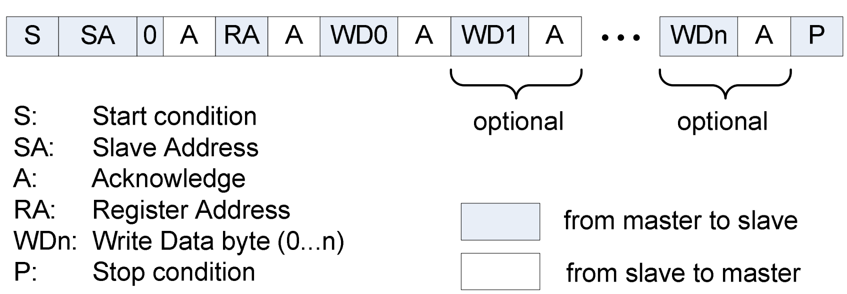

Figure 23: I2C Write

The register address is incremented automatically when successive register data (WD1...WDn) is supplied by the master.

5.3 I2C Read

The format of the I2C read is given in Figure 13. After the start condition [S], the slave address (SA) is sent, followed by an eighth bit (‘0’) indicating a Write. The SX9300 then Acknowledges [A] that it is being addressed, and the Master responds with an 8-bit Data consisting of the Register Address (RA). The Slave Acknowledges [A] and the master sends the Repeated Start Condition [Sr]. Once again, the slave address (SA) is sent, followed by an eighth bit (‘1’) indicating a Read. The SX9300 responds with an Acknowledge [A] and the read

Data byte (RD0). If the master needs to read more data it will acknowledge [A] and the SX9300 will send the next read byte (RD1). This sequence can be repeated until the master terminates with a NACK [N] followed by a stop [P].

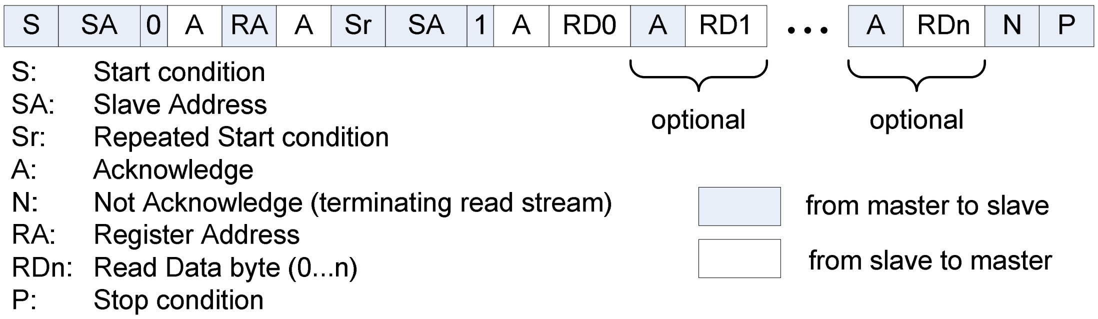

Figure 24: I2C Read

The register address is incremented automatically when successive register data (RD1...RDn) is retrieved by the master.

6 Reset

6.1 Power-up

During a power-up condition, the NIRQ output is HIGH until V_{DD} has met the minimum input voltage requirements and a T_{POR} time has expired upon which, NIRQ asserts to a LOW condition indicating the SX9300 is initialized. The host must perform an I2C read of RegIrqSrc to clear this NIRQ status. The SX9300 is then ready for normal I2C communication and is operational.

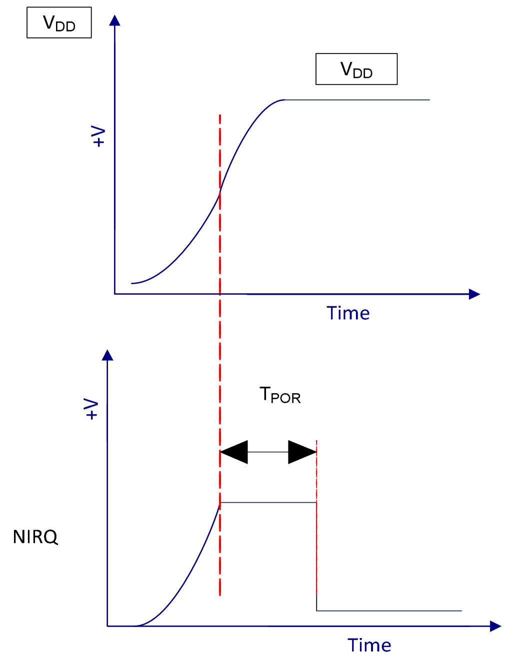

Figure 25: Power-up vs. NIRQ

6.2 NRST Pin

When the host asserts NRST LOW (for min. $T_{RESETPW}$) and then HIGH, the SX9300 will reset its internal registers and will become active after T_{POR}. When not used, this pin must be pulled high to SV_{DD}.

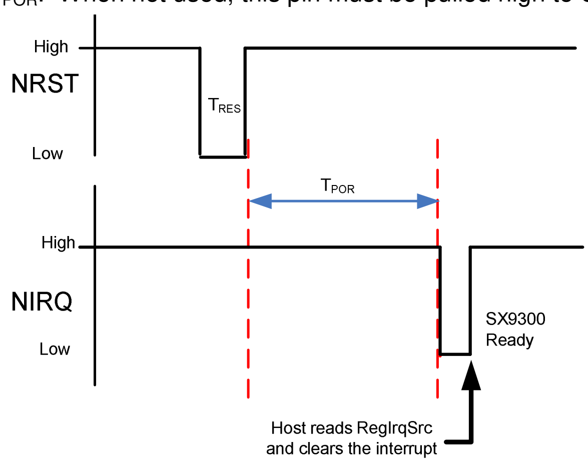

Figure 26: Hardware Reset